

HIGH PRESSURE COOLING NOZZLE FOR SEMICONDUCTOR PACKAGE

ABSTRACT

5 A fluid discharge method and apparatus is provided. The fluid discharge apparatus includes a first structure defining a first duct therein, a second structure defining a second duct therein and a third structure defining a third duct therein. Conduits formed in the structures, accurately positioned during machining thereof, extend from openings towards the ducts. Fluid in the ducts is initially directed into the conduits and subsequently out of the openings towards a cutting area comprising portions of a cutting blade and a workpiece being processed by the cutting blade. The conduits are shaped for generating a nozzle-type flow therethrough for accurate directional control of fluid streams discharged from the conduits. A method of forming the fluid discharge apparatus is also provided.

FIGURE 10